



FINAL PRODUCT/PROCESS CHANGE NOTIFICATIONGeneric Copy

09-Mar-2007**SUBJECT: ON Semiconductor Final Product/Process Change Notification #15739****TITLE: DPAK Package Added Capacity at Nantong Fujitsu****PROPOSED FIRST SHIP DATE: 09-May-07****AFFECTED CHANGE CATEGORY(S): Subcontractor Assembly Site****AFFECTED PRODUCT DIVISION(S): Power MOSFET Division****FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or Clara Cheng<Clara.Cheng@onsemi.com>**SAMPLES:**Contact your local ON Semiconductor Sales Office or Kathleen Van Tyne<k.vantyne@onsemi.com>**ADDITIONAL RELIABILITY DATA:** AvailableContact your local ON Semiconductor Sales Office or Donna Scheuch<d.scheuch@onsemi.com>**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This Process Change Notice is an extension to Process Change Notice # 15666 available at www.onsemi.com. PCN # 15666 announced that ON Semiconductor would be using Nantong Fujitsu Microelectronics Co. (NFME) as a manufacturing facility for their Low Voltage, N-Channel, MOSFET products. The Product portfolio being assembled at NFME will also include the Devices listed in this notification.

NFME's DPAK package meets JEDEC case outline standards, however, does have minor backside visual differences with other manufacturing facilities used by ON Semiconductor. In addition to NFME, ON Semiconductor will continue to manufacture DPAK products in their internal factory in Seremban, Malaysia, and external subcontractor ChipPac in Kuala Lumpur, Malaysia.

**Final Product/Process Change Notification #15739****RELIABILITY DATA SUMMARY:**

Reliability Test Results:

Test: HAST

Conditions: Temp= +130°C, 18.8 psi, RH=85% for 96 hrs.

Results: 0/231

Test: Intermittent Operating Life (IOL-PC)

Conditions: Ta=25°C, delta Tj=100°C, 2-min on/off, 7K-cycles

Results: 0/231

Test: Temperature Cycling (TC-PC)

Conditions: Ta=-65°C/150°C, Air-to-Air, Dwell >=10-min, 500-cy

Results: 0/231

Test: Autoclave Test (AC-PC)

Conditions: Ta=121°C, P=15psi, RH=100%, 96-Hrs

Results: 0/231

Test: Resistance to Solder Heat

Conditions: Ta=260°C, Dwell Time=10-Seconds,

Results: 0/30

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no change in electrical parametric performance. Characterization data is available upon request.

CHANGED PART IDENTIFICATION:

Product manufactured for ON Semiconductor at NFME will be marked with 'Nf' preceding the date code. Product will come from NFME at the expiration of this PCN. Date Code 0718.

AFFECTED DEVICES:

NTD4804N-1G
NTD4804NT4G
NTD4805N-1G
NTD4805NT4G
NTD4806N-1G
NTD4806NT4G
NTD4806NA-1G
NTD4806NA-1G
NTD4806NAT4G
NTD4808N-1G
NTD4808NT4G
NTD4809N-1G
NTD4809NT4G
NTD4809NA-1G
NTD4809NA-35G
NTD4809NAT4G
NTD4809NH-1G
NTD4809NH-35G
NTD4809NHT4G
NTD4810N-1G



Final Product/Process Change Notification #15739

NTD4810NT4G
NTD4810NH-1G
NTD4810NH-35G
NTD4810NHT4G
NTD4813N-1G
NTD4813NT4G
NTD4813NH-1G
NTD4813NH-35G
NTD4813NHT4G
NTD4815N-1G
NTD4815NT4G
NTD4815NH-1G
NTD4815NH-35G
NTD4815NHT4G